L Number	Hits	Search Text	DB	Time stamp
1	2	("5889326").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/10 09:16
2	9	("4724472" "4970570" "5028987" "5422516" "5508561" "5611481" "5640051" "5640052" "5641113").PN.	IBM_TDB USPAT	2004/09/10
3	27	5889326.URPN.	USPAT	2004/09/10
4	3540	((257/747) or (257/759) or (257/773) or (257/779)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/10 09:17
5	5624	organic adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/10 09:17
6	60	(((257/747) or (257/759) or (257/773) or (257/779)).CCLS.) and (organic adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/10 09:28
7	113	(257/474).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/10 .09:29
8	256	(257/747).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/10
	7	semiconductor adj substrate and organic adj substrate and pad and solder and ("coefficent of thermal expansion" or cte)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/10
-	6 0	("5471090" "6005292" "6046910" "6118181" "6232668" "6271597").PN. 6310403.URPN.	USPAT USPAT	2002/11/05 12:59 2002/11/05
-	6	 ("5471090" "6005292" "6046910" "6118181" "6232668" "6271597").PN.	USPAT	13:02 2002/11/05
-	9		USPAT	13:02 2002/11/05 13:02
_	5	6046910.URPN.	USPAT	2002/11/05
-	4345	"coefficent of thermal expansion" or cte	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/05 13:16
-	31	((257/786).CCLS.) and ("coefficent of thermal expansion" or cte)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/05 13:06
_	1299	c4 same solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05

-	169		USPAT;	2002/11/06
		cte) and (c4 same solder)	US-PGPUB;	13:55
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	327	gigapascal	USPAT;	2002/11/05
		9-9	US-PGPUB;	13:16
			EPO; JPO;	13.10
			DERWENT;	
			IBM_TDB	//
-	19	•	USPAT;	2002/11/05
		cte) and gigapascal	US-PGPUB;	13:18
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	0	underfill adj material same gigapascal	USPĀT;	2002/11/05
			US-PGPUB;	13:19
			EPO; JPO;	20.25
			DERWENT;	
		'		
]	464334	IBM_TDB	0000/11/05
_	775	underfill adj material	USPAT;	2002/11/05
			US-PGPUB;	13:19
	1		EPO; JPO;	ļ l
			DERWENT;	[[
			IBM TDB	
-	188	("coefficent of thermal expansion" or	USPAT;	2002/11/05
		cte) and (underfill adj material)	US-PGPUB;	13:19
		, (EPO; JPO;	
			DERWENT;	
	140		IBM_TDB	0000/11/05
_	143	conductive adj pad and solder and bump	USPAT;	2002/11/05
		and c4	US-PGPUB;	13:41
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	1235	(257/786).CCLS.	USPAT;	2002/11/06
		(, /, /	US-PGPUB;	09:10
			EPO; JPO;	1 03.10
			DERWENT;	
	105		IBM_TDB	
_	195		USPAT;	2002/11/06
		expansion" or cte)	US-PGPUB;	13:51
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	7841	(lead adj base adj solder) or (lead-tin)	USPAT;	2002/11/06
		or (pb adj sn or pbsn)	US-PGPUB;	14:46
		/ and or or brand	EPO; JPO;	
			DERWENT;	1
		/#	IBM_TDB	2002/11/05
-	20	1 '	USPAT;	2002/11/06
		cte) and (c4 same solder) and ((lead adj	US-PGPUB;	13:56
		base adj solder) or (lead-tin) or (pb adj	EPO; JPO;	
		sn or pbsn))	DERWENT;	
			IBM TDB	
-	2570	(lead adj base adj solder) or (lead-tin)	USPAT;	2002/11/06
		or (pb adj sn or pbsn) and c4	US-PGPUB;	15:00
		'En and English A.	EPO; JPO;	
			DERWENT;	
	14566	flin odi shin on flin-bi-	IBM_TDB	2002/11/06
-	14566	flip adj chip or flipchip	USPAT;	2002/11/06
			US-PGPUB;	14:47
			EPO; JPO;	
			DERWENT;	
	l		IBM TDB	
-	386	((lead adj base adj solder) or (lead-tin)	USPAT;	2002/11/06
		or (pb adj sn or pbsn) and c4) and (flip	US-PGPUB;	14:47
		adj chip or flipchip)	EPO; JPO;	=
		and outh of fithouth!		
			DERWENT;	
L	L		IBM TDB	L

-	245	((lead adj base adj solder) or (lead-tin)	USPAT;	2002/11/06
		or (pb adj sn or pbsn)) and c4	US-PGPUB;	15:01
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	69	larger near pad and smaller near pad and	USPAT;	2003/11/11
		solder	US-PGPUB;	10:14
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	6	("4673772" "5616520" "5761048"	USPAT	2003/11/11
		"5859407" "5907187" "6093964").PN.		10:23
-	1	6285083.URPN.	USPAT	2003/11/11
				10:25
-	2	6274474.URPN.	USPAT	2003/11/11
-				10:32
-	0	beriner.in.	USPAT;	2003/11/18
			US-PGPUB;	13:41
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	670	bernier.in.	USPAT;	2003/11/18
			US-PGPUB;	13:41
			EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	/ /
-	7	solder adj ball and bernier.in.	USPAT;	2003/11/18
			US-PGPUB;	13:43
			EPO; JPO;	
			DERWENT;	
	6005		IBM_TDB	0000 (11 (10
-	6925	carey.in. or gramatzki.in. or homa.in. or	USPAT;	2003/11/18
		langevin.in. or tran.in. or white.in	US-PGPUB;	13:44
			EPO; JPO; DERWENT;	
			IBM TDB	
_	20	 solder adj ball and (carey.in. or	USPAT;	2003/11/18
	20	gramatzki.in. or homa.in. or langevin.in.	US-PGPUB;	13:45
		or tran.in. or white.in)	EPO; JPO;	
1		02 02011.211. 02 1111100.2111	DERWENT;	
			IBM TDB	
1 -	57	5075965.URPN.	USPAT	2003/11/18
]			13:50
-	0	6330967.URPN.	USPAT	2003/11/18
				13:54
-	25	("4545610" "5060844" "5075965"	USPAT	2003/11/18
		"5161729" "5221038" "5234152"		13:54
		"5372298" "5429292" "5470787"		
		"5473814" "5580668" "5591941"		
		"5634268" "5639696" "5675889"		
		"5729896" "5796591" "5808853"		
		"5825629" "5912505" "5953623"		
		"5965945" "6121069" "6130476"		
		"6162660").PN.		
_	27	, , , , , , , , , , , , , , , , , , ,	USPAT;	2004/09/03
		electrode or pad) and solder adj ball and	US-PGPUB;	14:30
		semiconductor adj substrate	EPO; JPO;	
			DERWENT;	
L		<u> </u>	IBM_TDB	<u> </u>